

Supplier Name: Texas Instruments Inc. (DUNS# 00-732-1904)
 Contact Info: ti.com/support
 Form/Declaration Type: Distribute - RoHS and IEC 62474 DB
 Created on: 06/13/2022

Details for "UC2825DWG4"

Current Product Information

TI part number	Lead finish/Ball material	MSL rating/peak reflow	Assembly site	Package Pins	Package body size (mm)	Total device mass (mg)*
UC2825DWG4	NIPDAU	Level-2-260C-1 YEAR	Ext-Mfg	DW 16	10.3x7.5x2.45	479.4

*Total Device Mass

The summary mass is a rounded value and will be within approximately +/- 10% of the detailed mass value.

Environmental Ratings Information

RoHS	REACH	Green	IEC 62474 DB
Yes	Yes	Yes	Yes

Component Information

Component	Substance	CAS Number	Amount (mg)	Homogeneous Material Level		Component Level	
				Percentage %	ppm	Percentage %	ppm
Bond Wire							
Not Categorized	Proprietary Materials		0.000031	0.00734	73	0.000006	0
Precious Metals	Gold	7440-57-5	0.422288	99.99266	999927	0.088086	881
Sub-Total			0.422319	100	1000000	0.088092	881
Die Attach Adhesive							
Other Inorganic Materials	Silica	7631-86-9	0.030125	1.999976	20000	0.006284	63
Precious Metals	Silver	7440-22-4	1.039325	69.000005	690000	0.216795	2168
Thermoplastics	Epoxy	85954-11-6	0.436818	29.000019	290000	0.091117	911
Sub-Total			1.506268	100	1000000	0.314195	3142
Lead Frame							
Copper and Its Alloys	Copper	7440-50-8	136.360887	97.532999	975330	28.443785	284438
Copper and Its Alloys	Iron	7439-89-6	3.239398	2.317	23170	0.675712	6757
Copper and Its Alloys	Phosphorus	7723-14-0	0.034953	0.025	250	0.007291	73
Zinc and Its Alloys	Zinc	7440-66-6	0.174763	0.125	1250	0.036454	365
Sub-Total			139.810001	100	1000000	29.163243	291632
Lead Frame Plating							
Nickel and Its Alloys	Nickel	7440-02-0	1.702648	95.12	951200	0.355159	3552
Precious Metals	Gold	7440-57-5	0.013962	0.78	7800	0.002912	29
Precious Metals	Palladium	7440-05-3	0.07339	4.1	41000	0.015309	153
Sub-Total			1.79	100	1000000	0.37338	3734
Mold Compound							
Other Inorganic Materials	Fused Silica	60676-86-0	290.045738	87.7	877000	60.50121	605012
Other Plastics and Rubber	Carbon Black	1333-86-4	0.992175	0.3	3000	0.20696	2070
Thermoplastics	Epoxy	85954-11-6	39.686988	12	120000	8.278387	82784
Sub-Total			330.724901	100	1000000	68.986557	689866
Semiconductor Device							
Ceramics / Glass	Doped Silicon	7440-21-3	5.151365	100	1000000	1.074533	10745
Sub-Total			5.151365	100	1000000	1.074533	10745
Total			479.404854			100	1000000

Important Note

The ppm calculations are at the homogeneous material level and are maximum concentration values. The ppm displayed represents the homogeneous material with the highest ppm for that substance. The amount (mg) calculations represent the maximum total amount of each substance within the component.

The ppm calculations are at the component level and are average concentration values. The amount (mg) calculations represent the average total amount of each substance within the component.

[See Glossary of Terms for more details.](#)

Important Part Information

There is a remote possibility the Customer Part Number (CPN) your company uses could reference more than one TI part number. This is due to two or more users (EMSI or subcontractors) using the same CPN for different TI part numbers. If this occurs, please check your Customer Part Number and cross reference it with the TI part number seen on this page.

Product Content Methodology

[For an explanation of the methods used to determine material weights, see Product Content Methodology.](#)

Material Declaration Certificate for Semiconductor IC Packaged Products

TI certifies that the material content information provided by TI is representative and accurate to the best of their knowledge based on material information provided by its suppliers and their combination into finished IC packaged products. TI semiconductor products designated to be "Pb-free", "Green" or "RoHS Exempt" fully meets the latest EU RoHS Directive requirements along with other legislation as seen in the former JIG-101 list that has been transferred to the IEC 62474 database.

Important Information/Disclaimer

TI bases its material content information on information provided by third-party suppliers and has taken, and continues to take, reasonably diligent steps to provide any required or available information. TI may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers may consider certain information to be proprietary, and thus certain information may not be available for release by TI. The material content information is provided by TI "as is."

[For additional information, please contact TI customer support.](#)

Signature: [\(click here for a fuller statement with a signed certificate\)](#)

Name/Title: Hubie Payne, Vice President, Worldwide SC Quality

For further environmental statements, please go to www.ti.com/eoinfo

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RoHS: Means TI semiconductor products that are compliant with the current RoHS requirement that the maximum concentration values of the ten substances listed in RoHS Annex II do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI semiconductor products labeled as "RoHS Compliant" are suitable for use in specified lead-free processes. TI may also reference these types of semiconductor products as "Pb-Free." These TI semiconductor products are also fully compliant with GADSL and the IEC 62474 database for electronic requirements.

RoHS Exempt: Means TI semiconductor products that contain lead (Pb) above the RoHS Annex II threshold, but that fall within one of the specific RoHS exemptions noted above or documented in <http://www.ti.com/lit/pdf/szzq088>

Green: Means the content of Chlorine (Cl) and Bromine (Br)-based flame retardants meet JS709B low halogen requirements of <=1 000ppm threshold; Antimony trioxide (Sb2O3) contained in halogen based flame retardant materials meets the <=1 000ppm threshold requirement; and Beryllium Oxide (BeO) is <=1000ppm.